

3ni52

Bni52 Feature

Unit size :	700(W)x700(D)x689(H)mm (including cover)
Rotation of plate :	1-150rpm
Diameter of plate :	350mm
Applied Jig :	up to 4 inch jig
Sweep arm :	up to 2 arms (1arm standard)
Slurry feeding :	auto mixing and feeding
Timer :	Max. 99Hour 59Minutes
Operation :	Touch panel control
Net weight:	90kg (including cover)
Power Supply:	100V/240V
Consumption current:	10A/4A

Precision Materials Processing

3ni BN TECHNOLOGY CORPORATION
A MEMBER OF BN INTERNATIONAL GROUP

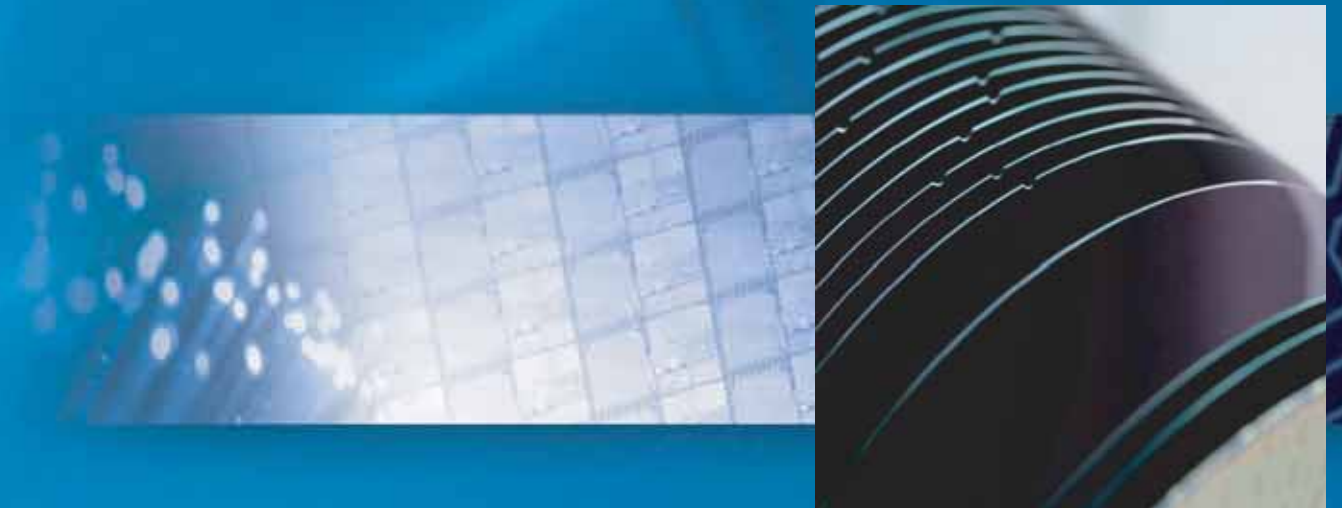
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Extreme precise Lapping/Polishing Machine

**Achieve extreme precise polishing
under nano-technology environment**



Bni52 System feature

Optimum system

Offer not only hardware but also optimum system as package including technology and know-how.

Capability for research laboratories up to small volume production

Bni52 covers extreme precise lapping and polishing with itself and can be used for research laboratories up to small volume production.

Accuracy

Bni52 achieved extreme high accuracy that is required in nano-technology material area.

Extreme precise CMP

Offer most optimum system under the condition that is required in planarization, uniformity of thickness.

Lapping/Polishing

BN offer best surface finish with unique and extreme precise jig / plate and background of technology, CMP etc.

Easy operation

All function, rotation of plate and abrasive auto feed etc. can be controlled with touch panel on 8.4 inch LCD panel.

Standard!!!

**Resistant to chemical
(Alkali and Acid)**

Equipped with the cover for clean room



2, 3, 4, 6 inch Jig

Polishing jig

Support samples firmly and control the pressure to the work. Jig can be customized with request. Bni52 can be applied for various application.



Addition to vacuum chuck type for wafer, holder can be customized to fit user's work.

Max capability: 4 inch jig and 2 sweep arms

Application

Leading edge semiconductor crystal material

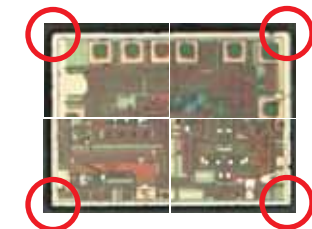
Piled up various experiences of lapping and polishing with leading edge semiconductor crystal material, compound semiconductor material as below.

- GaN
- Sapphire
- Crystal
- Indium Phosphorus
- SiC
- Zinc oxide
- GaAs
- Other various Oxide Crystal

Failure analysis/delaying

Capable for delayering, peeling off one layer by one layer extreme precisely. With delayering know-how of BN, offer polishing solution that essential to failure analysis. Extreme precise delayering with Bni52 shorten the process of failure analysis.

AL layer after delayering
(Capable of delayering Cu layer also)



Optical material

Capable for polishing various optical materials coating over surface of crystal and sapphire.

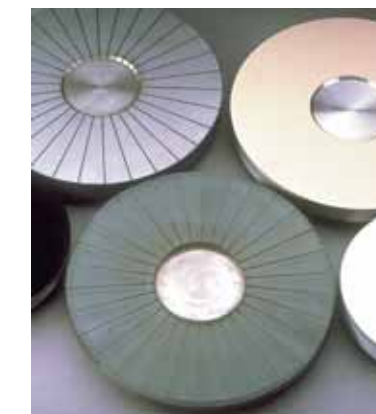


Polishing slurry

Offer optimum solution that is suitable to user's application with various polishing materials, lapping powder to CMP slurry.

Polishing plate

Offer optimum polishing plate that is suitable for user's works and objects.



Provide various plate.

- Cast iron
- Tin
- Plate for polishing cloth
- Glass
- Polyurethane

Provide optimum plate, other material, trench that is requested from users.